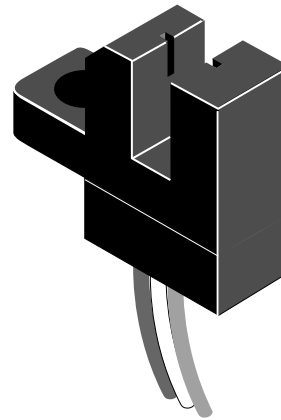
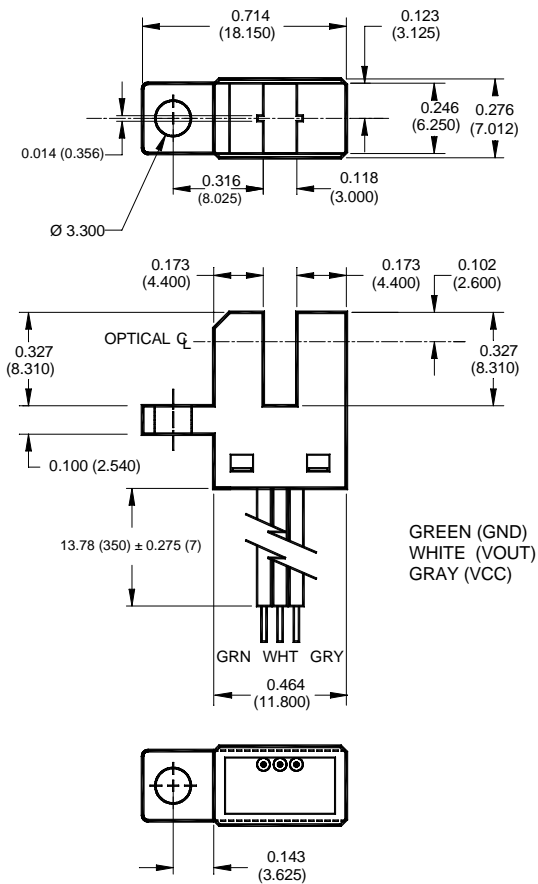


PACKAGE DIMENSIONS



FEATURES

- No contact switching
- Mounting tab
- Wire leads for remote connection
- 3 mm slot
- Output configuration: Inverter open-collector
- TTL/CMOS compatible output
- Aperture width: .014"

NOTES (Applies to Max Ratings and Characteristics Tables.)

1. Derate power dissipation linearly 1.67 mW/°C above 25°C.
2. Derate power dissipation linearly 2.50 mW/°C above 25°C.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.

NOTES:

1. Dimensions for all drawings are in inches (millimeters).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.
3. Wire gauge: 24 AWG, 7 strand, pre-tinned copper.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-40 to +85	°C
Storage Temperature	T_{STG}	-40 to +85	°C
Soldering Temperature (Iron) ^(3,4)	T_{SOL-I}	240 for 5 sec	°C
EMITTER			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	5	V
Power Dissipation ⁽¹⁾	P_D	100	mW
SENSOR			
Output Current	I_O	50	mA
Supply Voltage	V_{CC}	16	V
Output Voltage	V_O	30	V
Power Dissipation ⁽²⁾	P_D	150	mW

ELECTRICAL / OPTICAL CHARACTERISTICS (T _A =25°C)						
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNITS
Operating Supply Voltage		V _{CC}	4.5	—	16	V
INPUT DIODE						
Forward Voltage	I _F = 20 mA	V _F	—	—	1.7	V
Reverse Leakage Current	V _R = 5 V	I _R	—	—	10	μA
COUPLED						
Operating Supply Current	V _{CC} = 16 V	I _{CC}	—	—	12	mA
Low Level Output Voltage	V _{CC} = 5 V, R _L = 360 Ω	V _{OL}	—	—	0.4	V
High Level Output Current	V _{CC} = 5 V, V _{OH} = 30 V (Light Path Blocked)	I _{OH}	—	—	100	μA
Hysteresis Ratio			—	1.2	—	
Propagation Delay	V _{CC} = 5 V, R _L = 360 Ω	t _{PLH} , t _{PHL}	—	5	—	μs
Output Rise and Fall Time	V _{CC} = 5 V, R _L = 360 Ω	t _r , t _f	—	70	—	ns

Fig. 1 Output Voltage Vs. Shield Distance (Vertical)

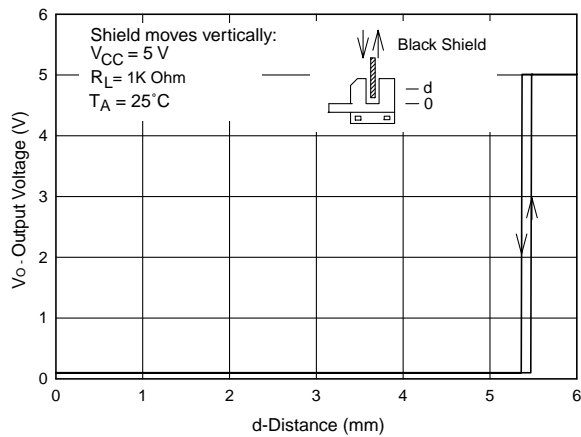


Fig. 2 Output Voltage vs. Shield Distance (Horizontal)

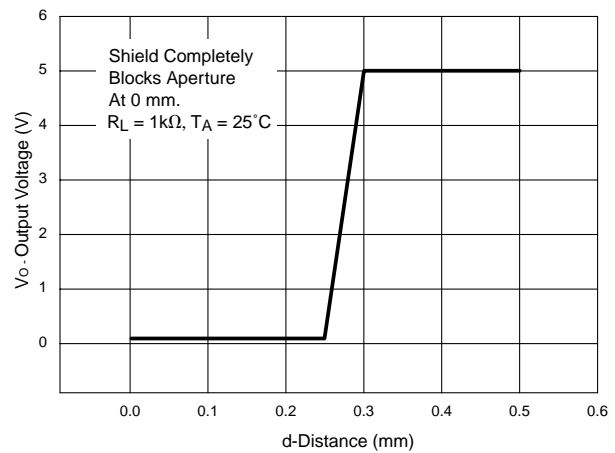


Fig. 3 Supply Current vs. Supply Voltage

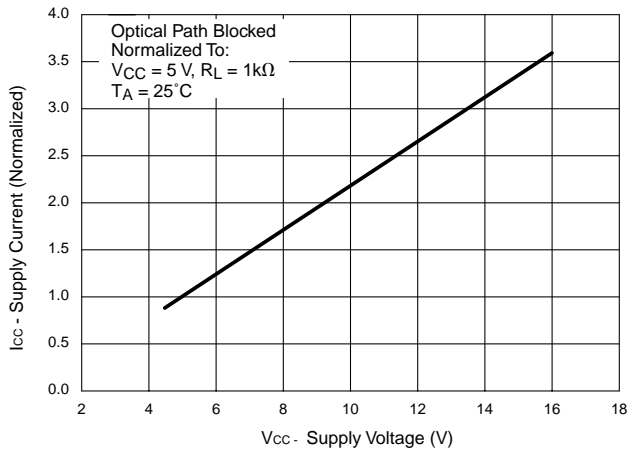


Fig. 4 Supply Current vs. Supply Voltage

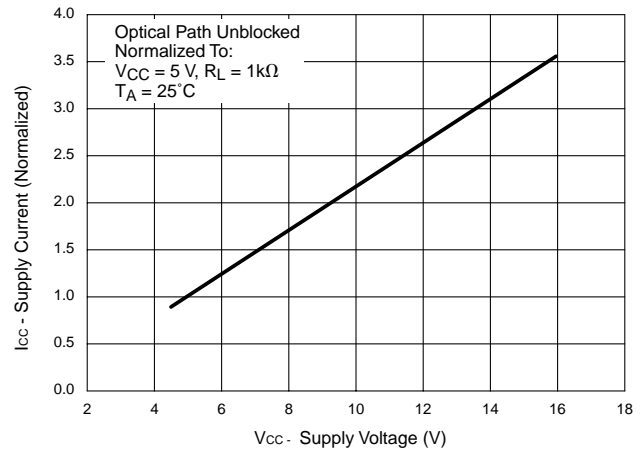


Fig. 5 Low Level Output Voltage vs. Supply Voltage

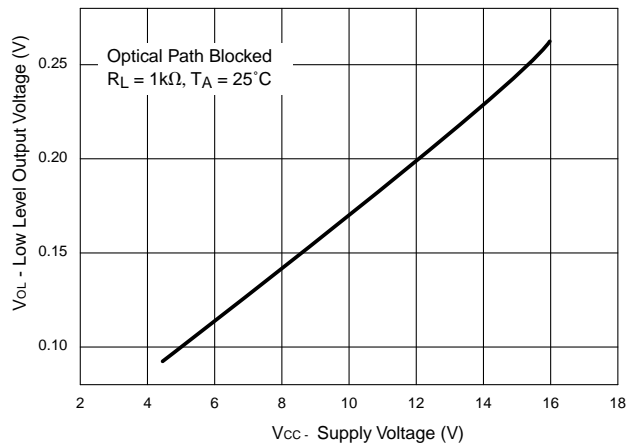


Fig. 6 Low Level Output Voltage vs. Load Resistance

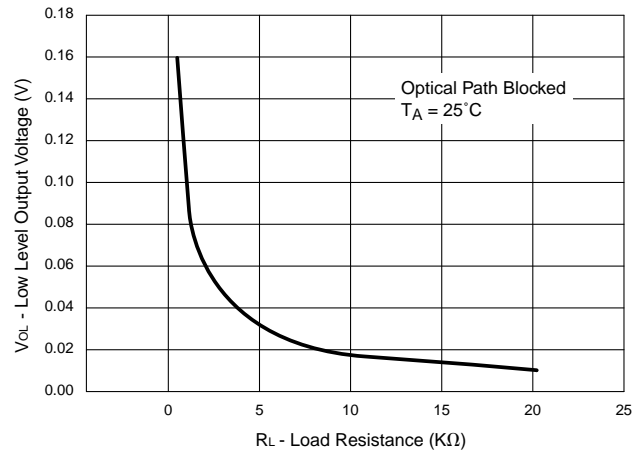


Fig. 7 Schematic

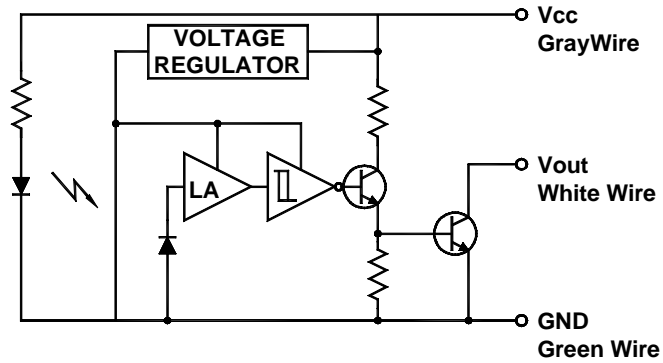
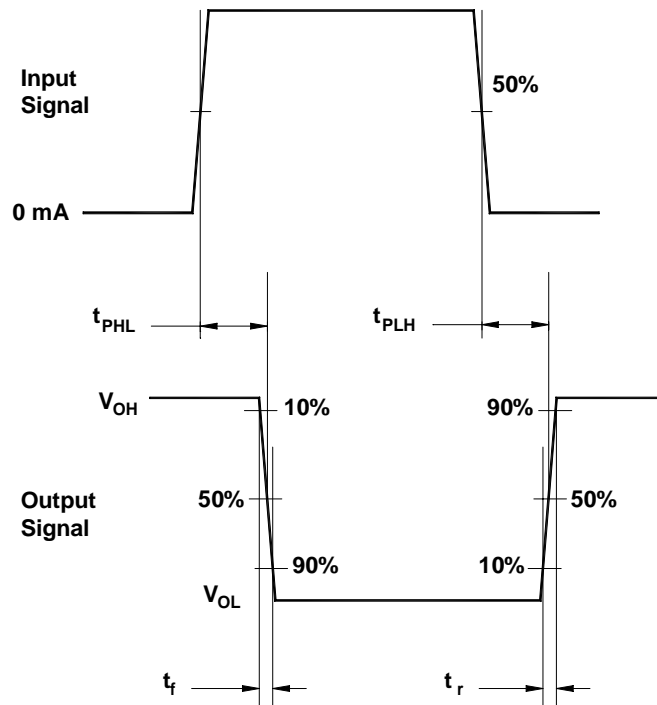


Fig. 8 Switching Test Curve for Inverters



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